

L Number	Hits	Search Text	DB	Time stamp
2	3254	(372/34,36,50,109).CCLS.	USPAT; US-PGPUB	2004/04/26 13:25
3	1927	((372/34,36,50,109).CCLS.) and semiconductor near3 laser	USPAT; US-PGPUB	2004/04/26 13:25
4	1622	((372/34,36,50,109).CCLS.) and semiconductor near3 laser) and (case casing base mount support)	USPAT; US-PGPUB	2004/04/26 13:26
5	1321	((372/34,36,50,109).CCLS.) and semiconductor near3 laser) and (case casing base mount\$4 hold\$4 support\$4) with laser	USPAT; US-PGPUB	2004/04/26 13:27
-	211	(semiconductor near2 laser) and (optical adj2 (pick adj2 up)) and laser with (mount mounting holder holding base substrate support)	USPAT; EPO; JPO; IBM_TDB	2003/03/02 18:51
-	2	5689108.URPN.	USPAT	2003/03/02 17:34
-	2	("5285062" "5374819").PN.	USPAT	2003/03/02 17:34
-	861	((372/36,109) or (369/44.12)).CCLS.	USPAT	2003/03/02 17:48
-	833	((372/36,109) or (369/44.12)).CCLS.) not ((semiconductor near2 laser) and (optical adj2 (pick adj2 up)) and laser with (mount mounting holder holding base substrate support))	USPAT; EPO; JPO; IBM_TDB	2003/03/02 17:49
-	592	((372/36,109) or (369/44.12)).CCLS.) and (laser with (mount base substrate holder case))	USPAT; EPO; JPO; IBM_TDB	2003/03/02 18:33
-	0	6459710.URPN.	USPAT	2003/03/02 17:53
-	10	("3698789" "4844581" "4945391" "5245620" "5631987" "5812715" "5920585" "6094515" "6243517" "6345059").PN.	USPAT	2003/03/02 17:54
-	3	5748658.URPN.	USPAT	2003/03/02 18:26
-	14	("4589010" "4768070" "4888307" "4945524" "5082339" "5089861" "5140572" "5291038" "5293038" "5309460" "5327443" "5361244" "5367530" "5446719").PN.	USPAT	2003/03/02 18:27
-	14	("4589010" "4768070" "4888307" "4945524" "5082339" "5089861" "5140572" "5291038" "5293038" "5309460" "5327443" "5361244" "5367530" "5446719").PN.	USPAT	2003/03/02 18:27
-	37	(ohyama tanaka).in. and (optical adj2 (pick adj2 up))	USPAT; EPO; JPO; IBM_TDB	2003/03/02 18:48
-	7	(fukada).in. and pioneer.as.	USPAT; EPO; JPO; IBM_TDB	2003/03/02 18:47
-	1630	pioneer.as. and laser	USPAT; EPO; JPO; IBM_TDB	2003/03/02 18:47
-	13	(pioneer.as. and laser) and fukuda.in.	USPAT; EPO; JPO; IBM_TDB	2003/03/02 18:47
-	42	(pioneer.as. and laser) and (optical adj2 (pick adj2 up))	USPAT; EPO; JPO; IBM_TDB	2003/03/02 18:48
-	173	(semiconductor near2 laser) and (optical adj2 (pick adj2 up)) and case and ((mount base substrate support holder) with laser)	USPAT; EPO; JPO; IBM_TDB	2003/03/02 19:11
-	0	6208610.URPN.	USPAT	2003/03/02 19:00
-	0	6208610.URPN.	USPAT	2003/03/02 19:00
-	4	6172958.URPN.	USPAT	2003/03/02 19:03
-	1477	(semiconductor near2 laser) with module	USPAT; EPO; JPO; IBM_TDB	2003/03/02 19:11
-	365	((semiconductor near2 laser) with module) and (casing case) and optical near3 system	USPAT; EPO; JPO; IBM_TDB	2003/03/02 19:13

-	6	((semiconductor near2 laser) with module) and (casing case) and optical near3 system) and optical adj2 (pick adj2 up)	USPAT; EPO; JPO; IBM_TDB	2003/03/02 19:13
-	2355	((semiconductor diode) near2 laser) and ((mount\$3 fix\$4 attach\$3) with (adhesive))	USPAT; EPO; JPO; IBM_TDB	2003/03/03 16:51
-	1191	((semiconductor diode) near2 laser) and ((mount\$3 fix\$4 attach\$3) with (adhesive))) and (mount\$3 fix\$4 attach\$3) with laser	USPAT; EPO; JPO; IBM_TDB	2003/03/03 16:52
-	42	((semiconductor diode) near2 laser) and ((mount\$3 fix\$4 attach\$3) with (adhesive))) and (optical adj2 (pick adj2 up))	USPAT; EPO; JPO; IBM_TDB	2003/03/03 16:52
-	1	(((semiconductor diode) near2 laser) and ((mount\$3 fix\$4 attach\$3) with (adhesive))) and (optical adj2 (pick adj2 up))) and (((semiconductor diode) near2 laser) and ((mount\$3 fix\$4 attach\$3) with (adhesive))) and (mount\$3 fix\$4 attach\$3) with laser and adhesive with thermal)	USPAT; EPO; JPO; IBM_TDB	2003/03/03 16:53
-	91	(((semiconductor diode) near2 laser) and ((mount\$3 fix\$4 attach\$3) with (adhesive))) and (mount\$3 fix\$4 attach\$3) with laser and adhesive with thermal	USPAT; EPO; JPO; IBM_TDB	2003/03/03 16:54
-	26860	((laser diode) and (case module)).ab.	USPAT; EPO; JPO; IBM_TDB	2003/08/21 14:44
-	1598	((laser diode) and (case module)).ab.) and 372/\$.ccls.	USPAT; EPO; JPO; IBM_TDB	2003/08/21 14:36
-	620	(((laser diode) and (case module)).ab.) and 372/\$.ccls.) and semiconductor.ab.	USPAT; EPO; JPO; IBM_TDB	2003/08/21 14:37
-	30	(((laser diode) and (case module)).ab.) and 372/\$.ccls.) and semiconductor.ab.) and hole.ab.	USPAT; EPO; JPO; IBM_TDB	2003/08/21 14:38
-	28	(((laser diode) and (case module)).ab.) and 372/\$.ccls.) and semiconductor.ab.) and hole with (case module)	USPAT; EPO; JPO; IBM_TDB	2003/08/21 14:42
-	13	(((laser diode) and (case module)).ab.) and 372/\$.ccls.) and semiconductor.ab.) and opening with (case module)	USPAT; EPO; JPO; IBM_TDB	2003/08/21 14:42
-	13731	((laser diode) with (case module)).ab.	USPAT; EPO; JPO; IBM_TDB	2003/08/21 14:44
-	1159	((laser diode) with (case module)).ab.) and (hole opening).ab.	USPAT; EPO; JPO; IBM_TDB	2003/08/21 14:44
-	679	((laser diode) with (case module)).ab.) and ((hole opening) with (case module)).ab.	USPAT; EPO; JPO; IBM_TDB	2003/08/21 14:46
-	40	(((laser diode) with (case module)).ab.) and ((hole opening) with (case module)).ab.) and 372/\$.ccls.	USPAT; EPO; JPO; IBM_TDB	2003/08/21 14:50
-	146	semiconductor with laser with module and module with (opening hole)	USPAT; EPO; JPO; IBM_TDB	2003/08/21 14:52
-	51	372/36,109.cccls. and (case module) with (hole opening)	USPAT; EPO; JPO; IBM_TDB	2003/08/21 15:26
-	16	4567598.URPN.	USPAT	2003/08/21 15:05
-	3	("3816847" "3869702" "4295152").PN.	USPAT	2003/08/21 15:06
-	1	5590144.pn. and adhesive	USPAT; EPO; JPO; IBM_TDB	2003/08/21 15:29

-	1	5590144.pn. and conductivity	USPAT; EPO; JPO; IBM_TDB	2003/08/21 15:30
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